

SMF5.0AT1G Series, SZSMF5.0AT1G Series

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Maximum P_{pk} Dissipation (PW=10/1000 μ s) (Note 1) SMF5.0A – SMF58A	P_{pk}	200	W
Maximum P_{pk} Dissipation @ $T_A = 25^\circ\text{C}$, (PW=8/20 μ s) (Note 2)	P_{pk}	1000	W
DC Power Dissipation @ $T_A = 25^\circ\text{C}$ (Note 3) Derate above 25°C Thermal Resistance, Junction-to-Ambient (Note 3)	P_D $R_{\theta JA}$	385 4.0 325	mW mW/ $^\circ\text{C}$ $^\circ\text{C}/\text{W}$
Thermal Resistance, Junction-to-Lead (Note 3)	$R_{\theta Jcathode}$	26	$^\circ\text{C}/\text{W}$
Operating and Storage Temperature Range	T_J, T_{stg}	-55 to +150	$^\circ\text{C}$

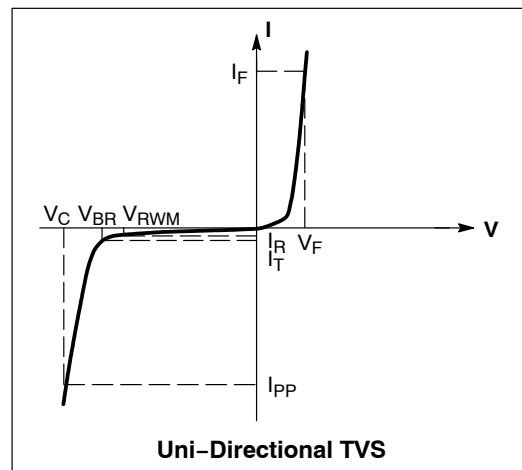
Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. Non-repetitive current pulse at $T_A = 25^\circ\text{C}$, per waveform of Figure 2.
2. Non-repetitive current pulse at $T_A = 25^\circ\text{C}$, per waveform of Figure 3.
3. Mounted with recommended minimum pad size, DC board FR-4.

ELECTRICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$ unless otherwise noted, $V_F = 3.5\text{ V}$ Max. @ I_F (Note 4) = 12 A)

Symbol	Parameter
I_{PP}	Maximum Reverse Peak Pulse Current
V_C	Clamping Voltage @ I_{PP}
V_{RWM}	Working Peak Reverse Voltage
I_R	Maximum Reverse Leakage Current @ V_{RWM}
V_{BR}	Breakdown Voltage @ I_T
I_T	Test Current
I_F	Forward Current
V_F	Forward Voltage @ I_F

4. 1/2 sine wave (or equivalent square wave), PW = 8.3 ms, duty cycle = 4 pulses per minute maximum.



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ELECTRICAL CHARACTERISTICS ($T_L = 30^\circ\text{C}$ unless otherwise noted, $V_F = 1.25$ Volts @ 200 mA)

Device*	Marking	V_{RWM} (V)	V_{BR} @ I_T (V) (Note 6)			I_T	I_R @ V_{RWM}	$V_C(\text{Max})$	$I_{PP}(\text{Max})$ (A)
		(Note 5)	Min	Nom	Max	(mA)	(μA)	(V)	(Note 7)
SMF5.0AG	KE	5	6.4	6.7	7	10	400	9.2	21.7
SMF6.0AG	KG	6	6.67	7.02	7.37	10	400	10.3	19.4
SMF6.5AG	KK	6.5	7.22	7.6	7.98	10	250	11.2	17.9
SMF7.0AG	KM	7	7.78	8.2	8.6	10	100	12	16.7
SMF7.5AG	KP	7.5	8.33	8.77	9.21	1	50	12.9	15.5
SMF8.0AG	KR	8	8.89	9.36	9.83	1	25	13.6	14.7
SMF9.0AG	KV	9	10	10.55	11.1	1	5	15.4	13.0
SMF10AG	KX	10	11.1	11.7	12.3	1	2.5	17	11.8
SMF11AG	KZ	11	12.2	12.85	13.5	1	2.5	18.2	11.0
SMF12AG	LE	12	13.3	14	14.7	1	2.5	19.9	10.1
SMF13AG	LG	13	14.4	15.15	15.9	1	1	21.5	9.3
SMF14AG	LK	14	15.6	16.4	17.2	1	1	23.2	8.6
SMF15AG	LM	15	16.7	17.6	18.5	1	1	24.4	8.2
SMF18AG	LT	18	20	21	22.1	1	1	29.2	6.8
SMF20AG	LV	20	22.2	23.35	24.5	1	1	32.4	6.2
SMF22AG	LX	22	24.4	25.6	26.9	1	1	35.5	5.6
SMF24AG	LZ	24	26.7	28.1	29.5	1	1	38.9	5.1
SMF26AG	ME	26	28.9	30.4	31.9	1	1	42.1	4.8
SMF28AG	MG	28	31.1	32.8	34.4	1	1	45.4	4.4
SMF30AG	MK	30	33.3	35.1	36.8	1	1	48.4	4.1
SMF33AG	MM	33	36.7	38.7	40.6	1	1	53.3	3.8
SMF36AG	MP	36	40	42.1	44.2	1	1	58.1	3.4
SMF48AG	MX	48	53.3	56.1	58.9	1	1	77.4	2.6
SMF51AG	MZ	51	56.7	59.7	62.7	1	1	82.4	2.4
SMF58AG	NG	58	64.4	67.8	71.2	1	1	93.6	2.1

5. A transient suppressor is normally selected according to the Working Peak Reverse Voltage (V_{RWM}) which should be equal to or greater than the DC or continuous peak operating voltage level.

6. V_{BR} measured at pulse test current I_T at ambient temperature of 25°C .

7. Surge current waveform per Figure 2 and derate per Figure 3.

*Include SZ-prefix devices where applicable.

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TYPICAL PROTECTION CIRCUIT

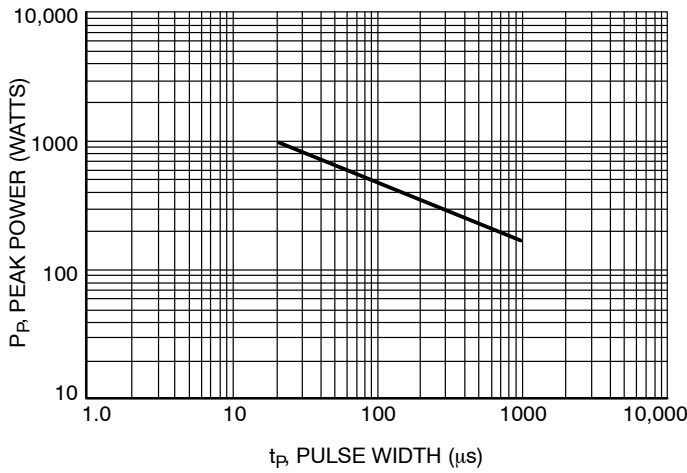
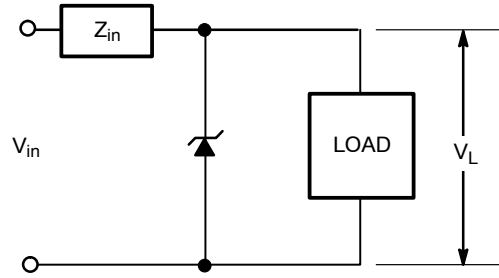


Figure 1. Pulse Rating Curve

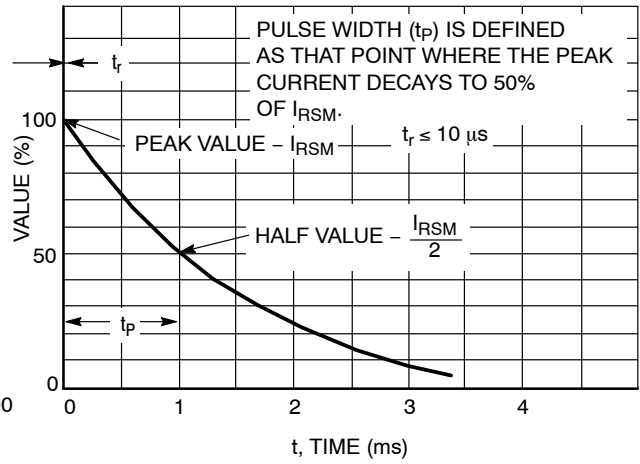


Figure 2. 10 X 1000 μs Pulse Waveform

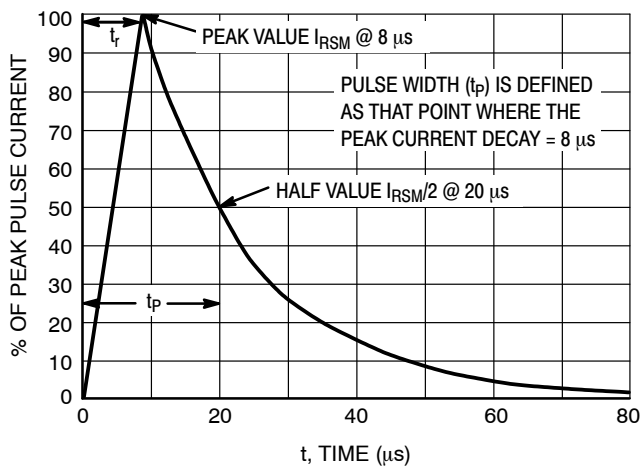


Figure 3. 8 X 20 μs Pulse Waveform

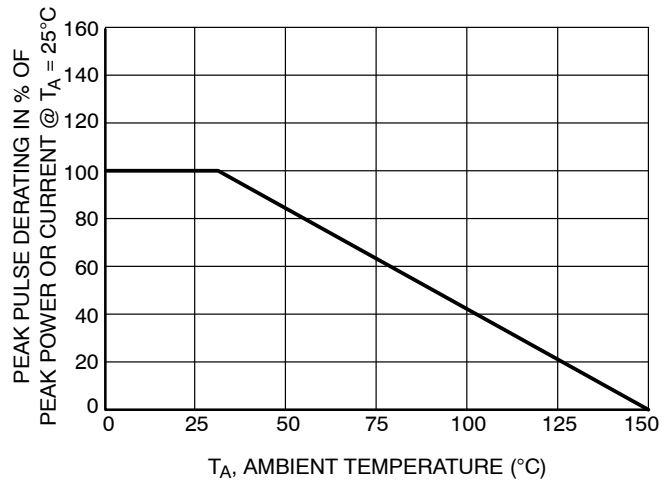


Figure 4. Pulse Derating Curve

SMF5.0AT1G Series, SZSMF5.0AT1G Series

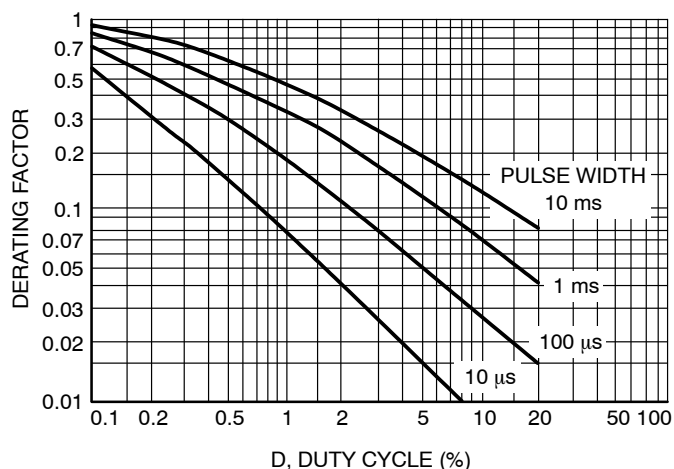


Figure 5. Typical Derating Factor for Duty Cycle

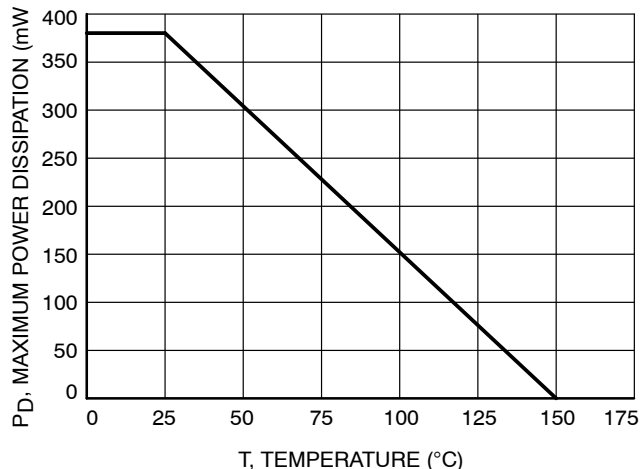


Figure 6. Steady State Power Derating

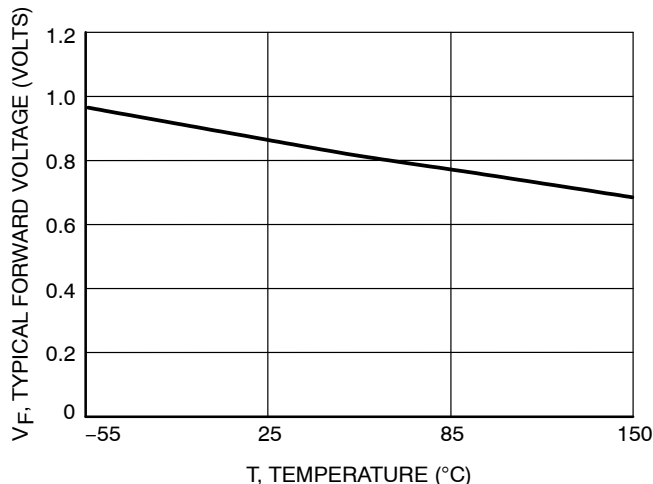


Figure 7. Forward Voltage

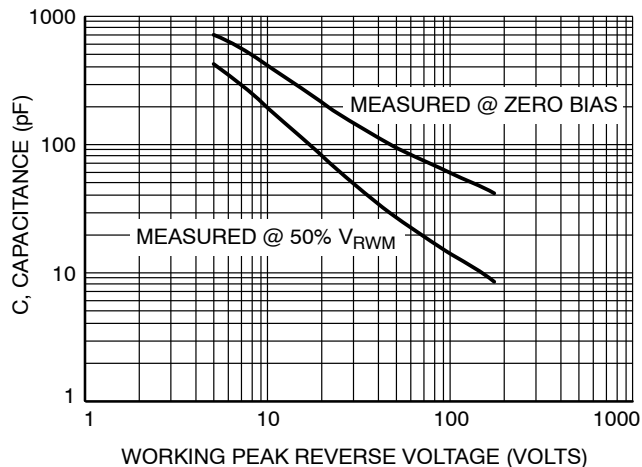
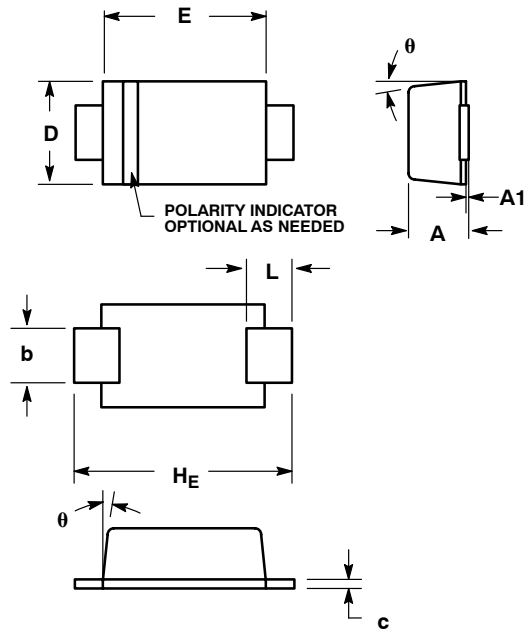


Figure 8. Capacitance versus Working Peak Reverse Voltage

SMF5.0AT1G Series, SZSMF5.0AT1G Series

PACKAGE DIMENSIONS

SOD-123FL
CASE 498-01
ISSUE B

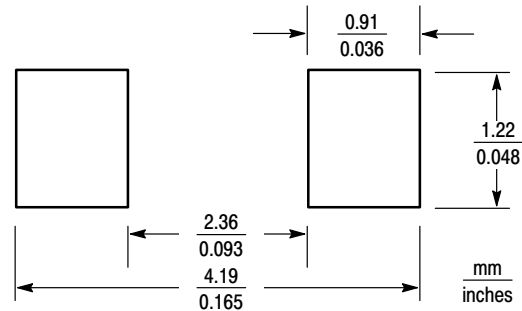


NOTES:


1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH.
4. DIMENSIONS D AND J ARE TO BE MEASURED ON FLAT SECTION OF THE LEAD: BETWEEN 0.10 AND 0.25 MM FROM THE LEAD TIP.

DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.90	0.95	1.00	0.035	0.037	0.039
A1	0.00	0.05	0.10	0.000	0.002	0.004
b	0.70	0.90	1.10	0.028	0.035	0.043
c	0.10	0.15	0.20	0.004	0.006	0.008
D	1.50	1.65	1.80	0.059	0.065	0.071
E	2.50	2.70	2.90	0.098	0.106	0.114
L	0.55	0.75	0.95	0.022	0.030	0.037
H_E	3.40	3.60	3.80	0.134	0.142	0.150
θ	0°	—	8°	0°	—	8°

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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